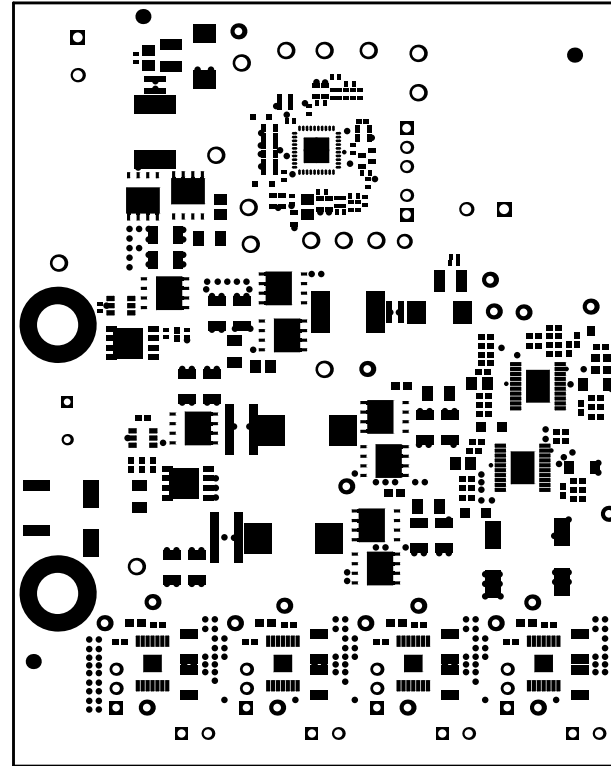
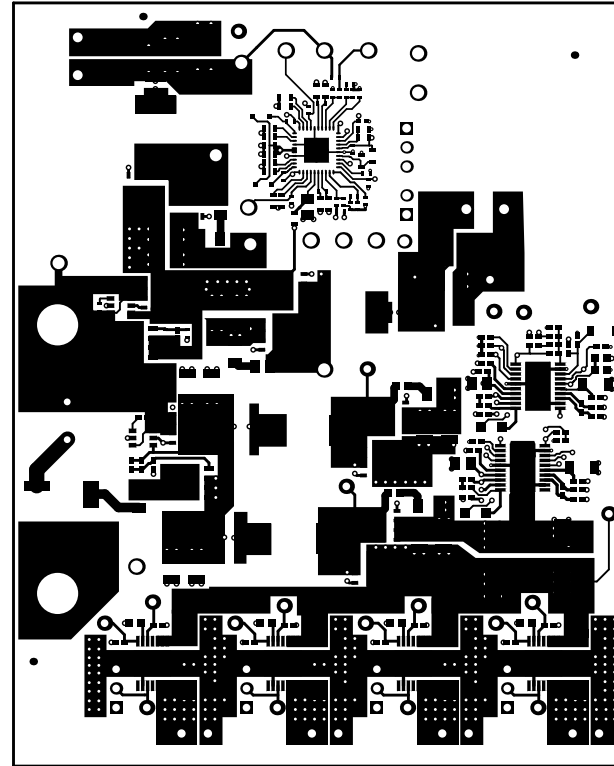


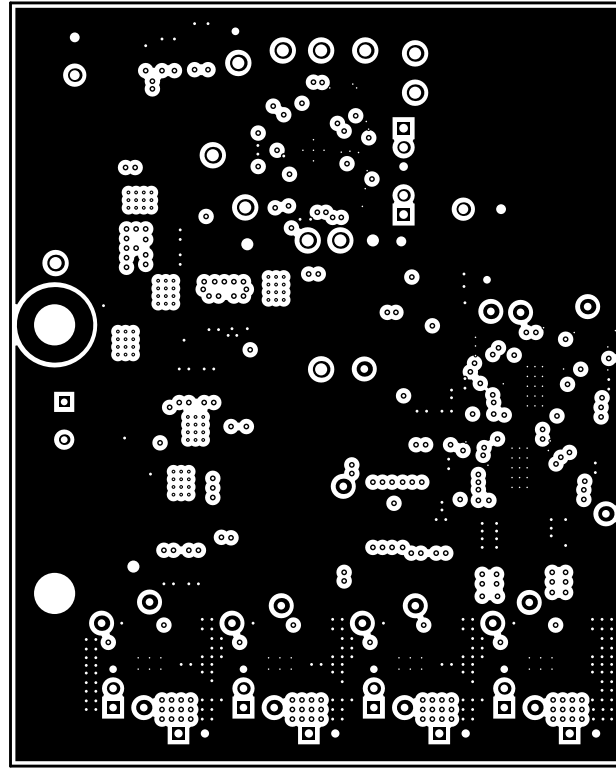
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME = Top Overlay	TID #: TIDA-01534		
PLOT NAME = Top Overlay	GENERATED : 12/19/2017 11:29:03 AM	TEXAS INSTRUMENTS	



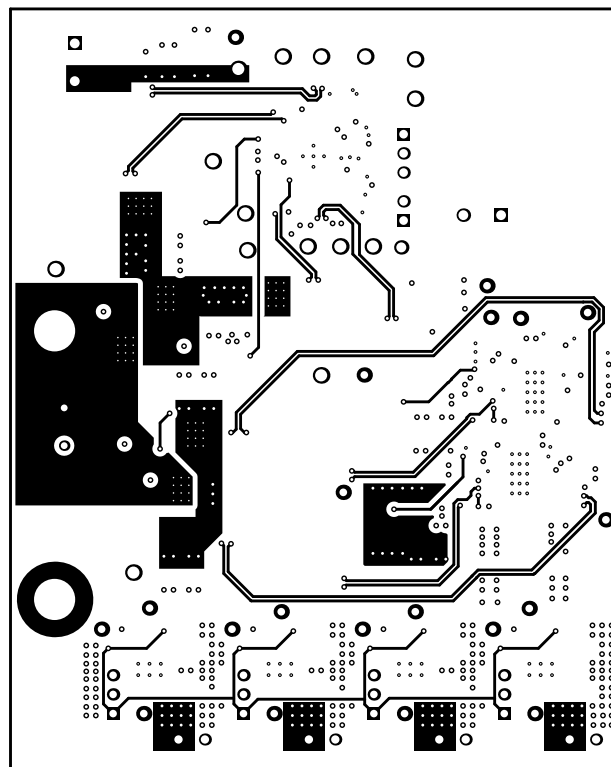
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME = Top Solder	TID #: TIDA-01534		
PLOT NAME = Top Solder Mask	GENERATED : 12/19/2017 11:29:04 AM	TEXAS INSTRUMENTS	



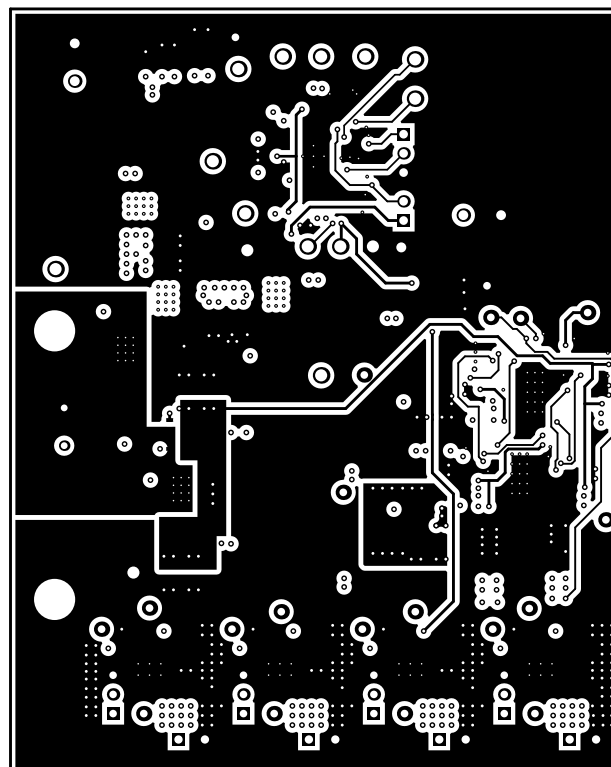
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME = Top Layer	TID #: TIDA-01534		
PLOT NAME = Top Layer	GENERATED : 12/19/2017 11:29:05 AM	TEXAS INSTRUMENTS	



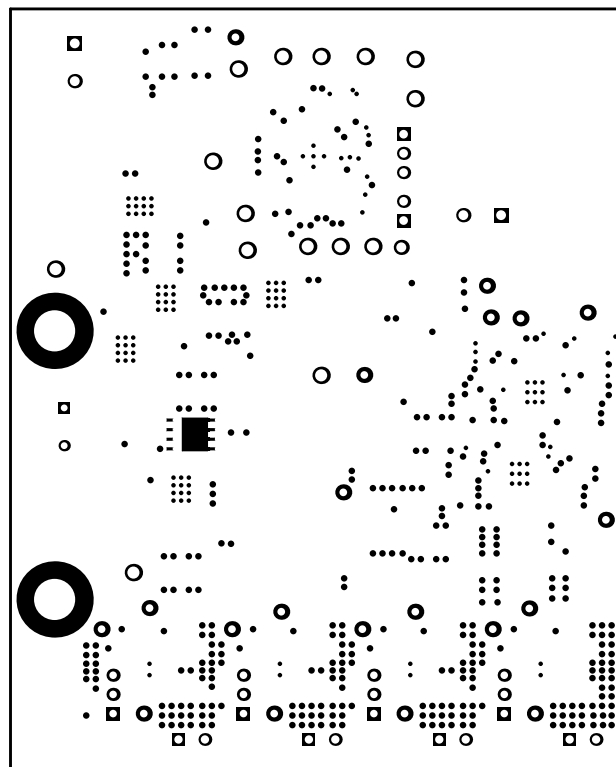
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME =	TID #: TIDA-01534		
PLOT NAME = Signal Layer 1	GENERATED : 12/19/2017 11:29:06 AM	TEXAS INSTRUMENTS	



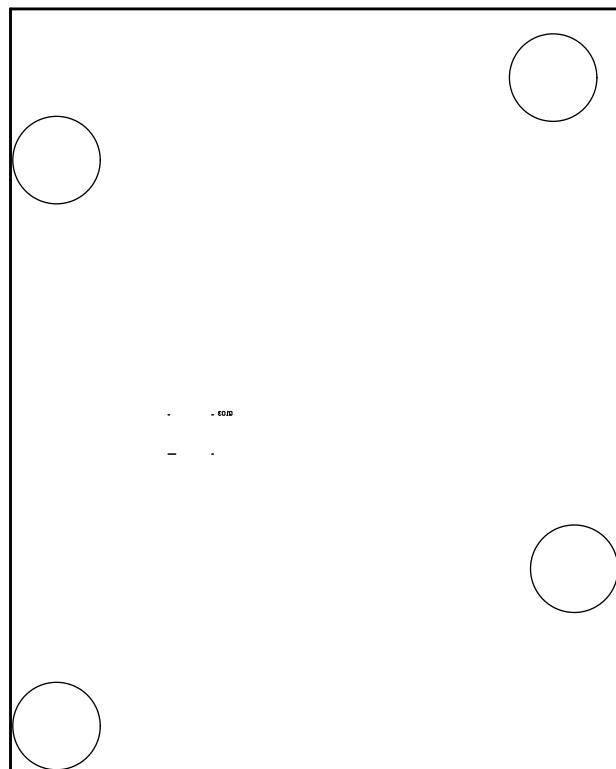
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME =	TID #: TIDA-01534		
PLOT NAME = Signal Layer 2	GENERATED : 12/19/2017 11:29:07 AM		TEXAS INSTRUMENTS



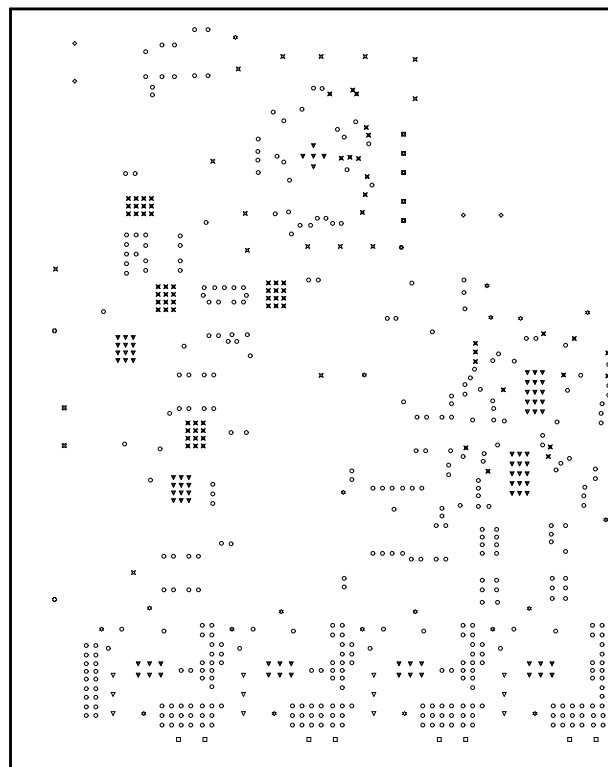
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME = Bottom Layer	TID #: TIDA-01534		
PLOT NAME = Bottom Layer	GENERATED : 12/19/2017 11:29:07 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME = Bottom Solder	TID #: TIDA-01534		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/19/2017 11:29:08 AM	TEXAS INSTRUMENTS	

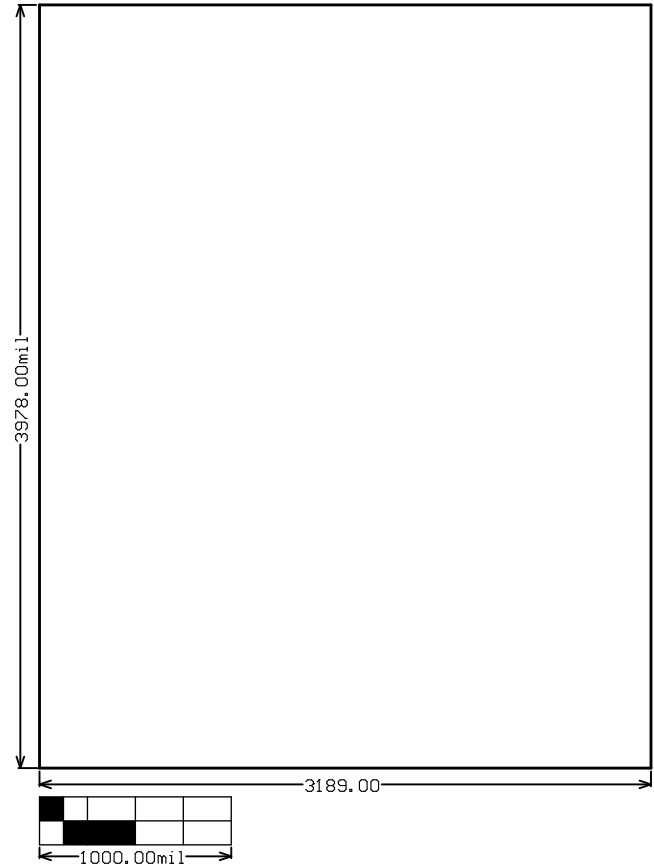


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME = Bottom Overlay	TID #: TIDA-01534		
PLOT NAME = Bottom Overlay	GENERATED : 12/19/2017 11:29:09 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	83	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
✕	73	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
○	403	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
▽	12	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
☆	20	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
■	5	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
●	1	52.00mil (1.321mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	15	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	214.57mil (5.450mm)	PTH	Round	Top Layer - Bottom Layer	
	628 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME = Drill Drawing	TID #: TIDA-01534		
PLOT NAME = Drill Drawing	GENERATED : 12/19/2017 11:29:10 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01534	REV: A	SUN REV: 3503
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01534		
PLOT NAME = Board Dimensions	GENERATED : 12/19/2017 11:29:12 AM	TEXAS INSTRUMENTS	

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